

FIG. 1

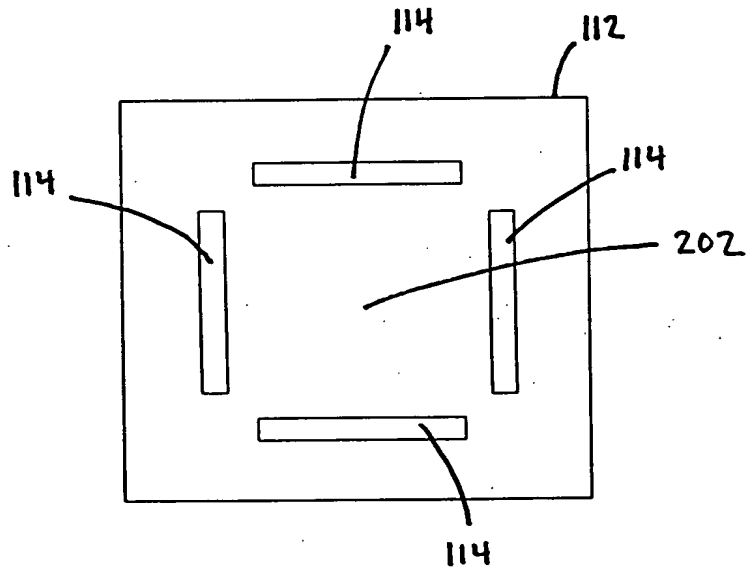


FIG. 2

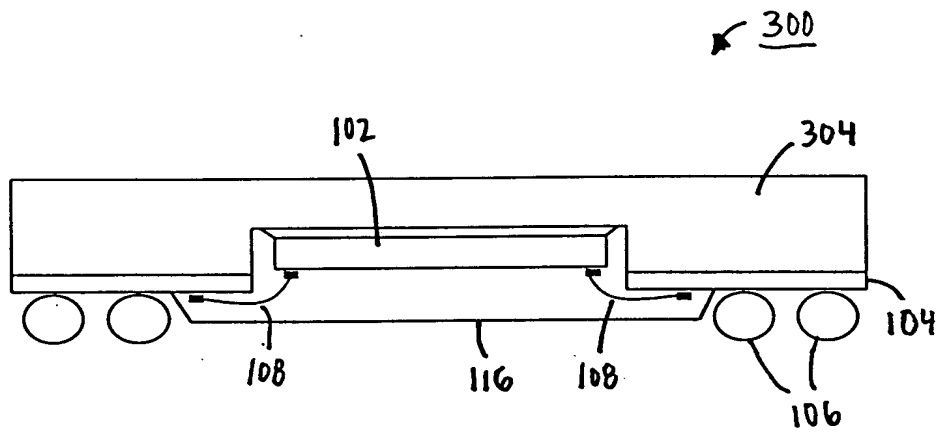


FIG. 3

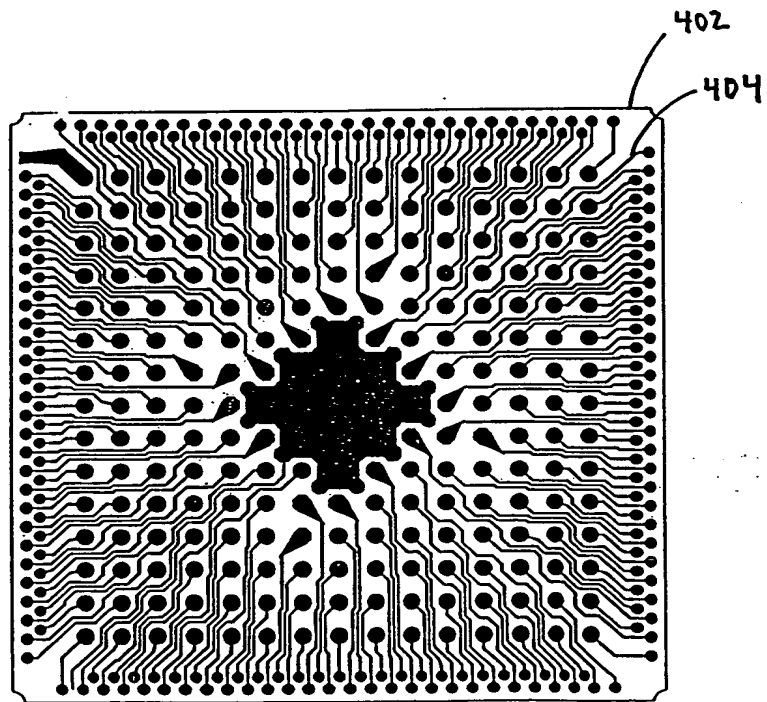


FIG. 4

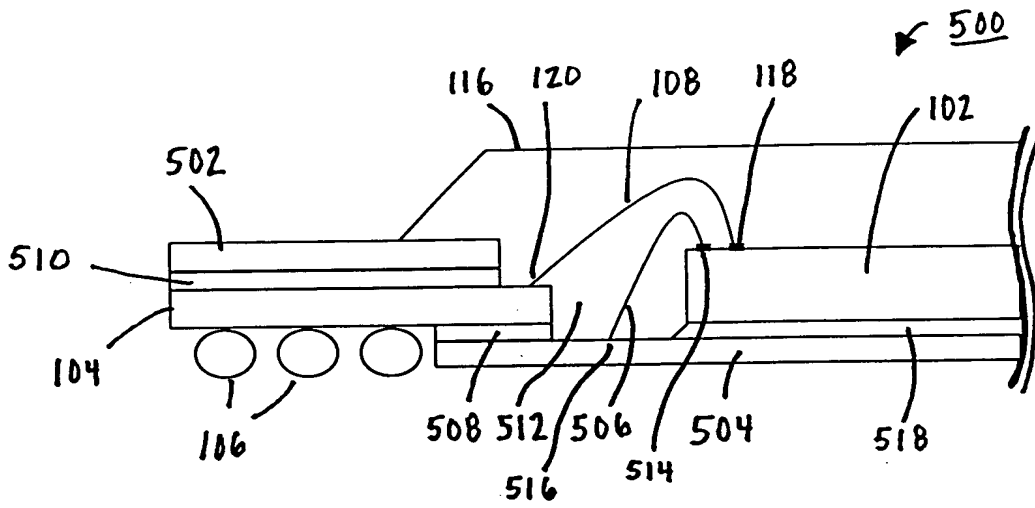


FIG. 5

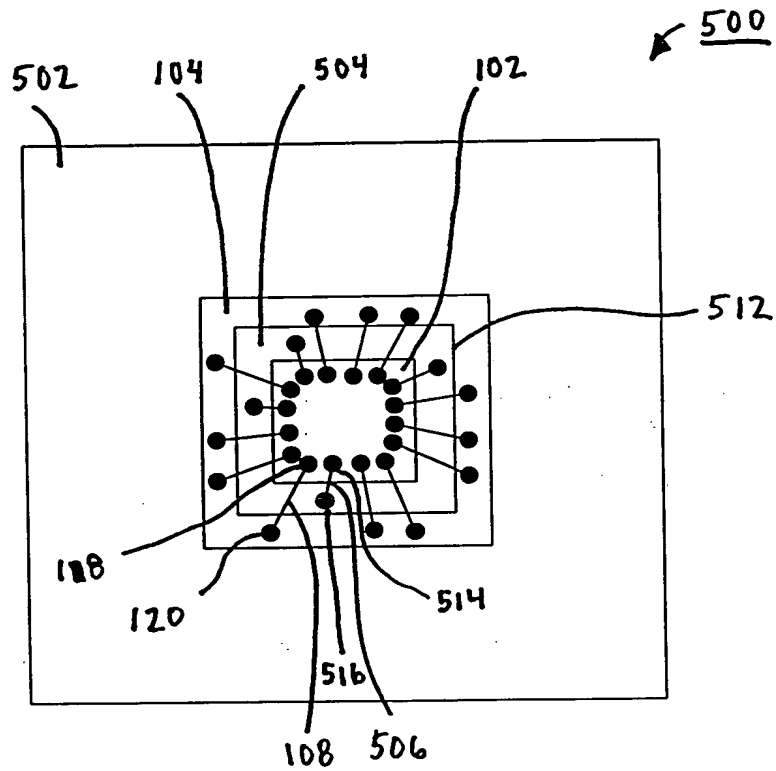


FIG. 6



09849537 050701 002050 22564860

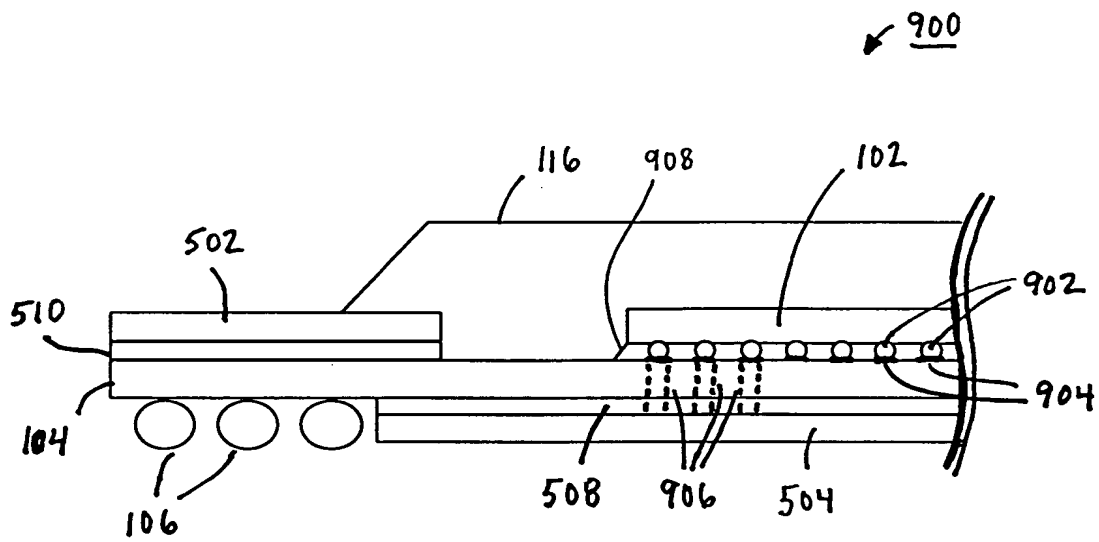


FIG. 9

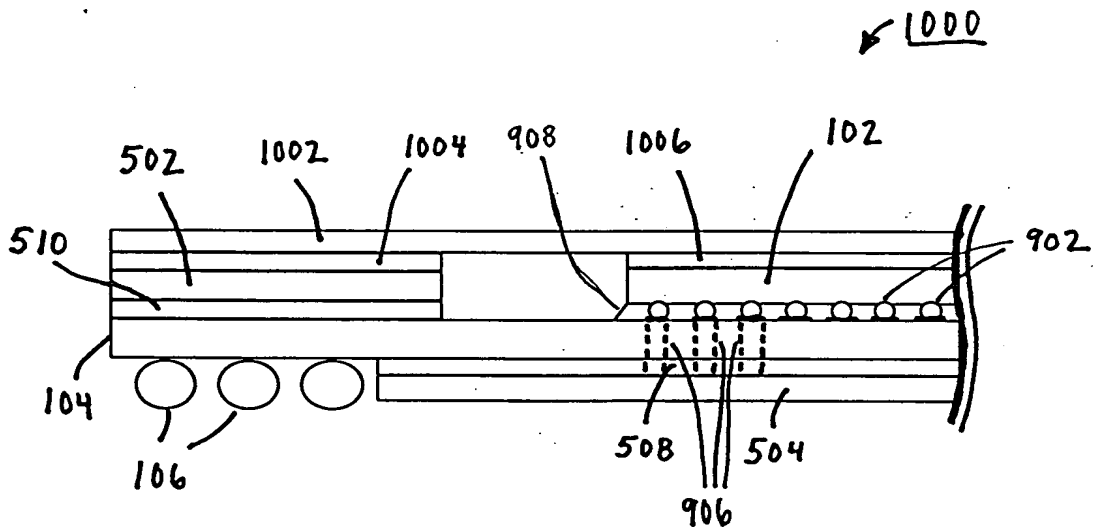


FIG. 10

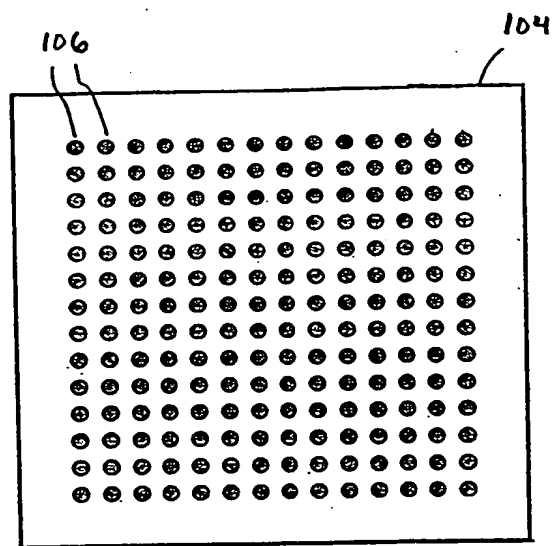


FIG. 11

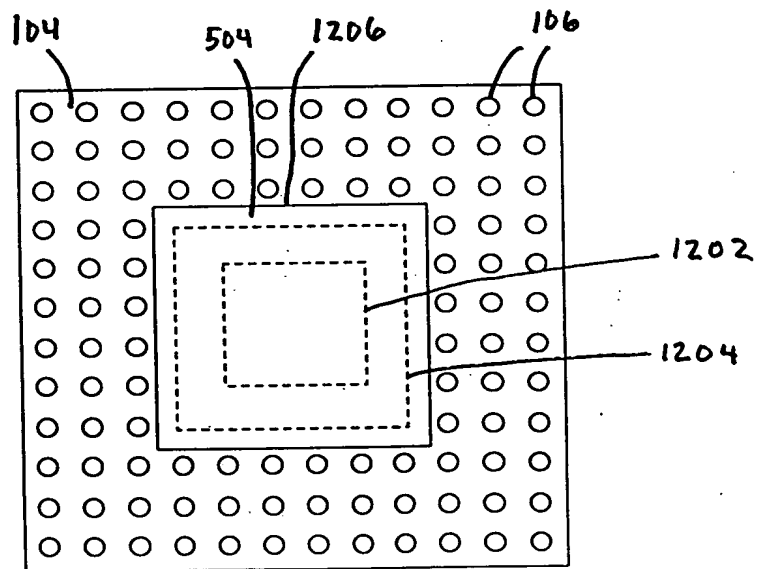


FIG. 12

1300

1302

a substrate that has a first surface and a second surface is received

1304

a first surface of a heat spreader is attached to the second substrate surface

1306

a second surface of the heat spreader is configured to be coupled to a printed circuit board (PCB)

1308

a plurality of solder balls are attached to the second substrate surface outside an outer dimensional profile of the heat spreader

FIG. 13

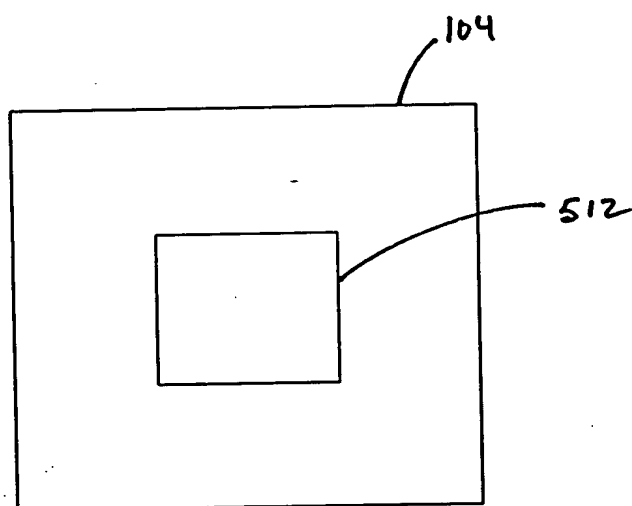


FIG. 14